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| Form PTO-1449<br>**INFORMATION DISCLOSURE CITATION**<br>*(Use several sheets if necessary)* | Attorney Docket No.<br>**62020-1400** | Serial No.<br>**10/699,230** |
| | Applicant<br>**Bakir, et al.** | |
| | Filing Date<br>**10/31/03** | Group<br>**TBD** |

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